

ABSTRACT OF THE INVENTION

A cover is employed with an edge mount electrical header connector to secure the header connector to a printed circuit board during soldering. The header connector includes plural electrical contacts supported in an insulative housing. The contacts include extending solder tails for engagement with solder pads of the printed circuit board. The cover includes an elongate insulative body for attachment to the header connector. The body of the cover includes gripper arms extending therefrom and being in spaced opposition to the extending solder tails. The solder tails and the gripper arms form a space therebetween for receiving an edge of the printed circuit board. The gripper arms and solder tails retain the printed circuit board edge so as to permit secure soldering of the solder tails to the solder pads of the printed circuit board.

